



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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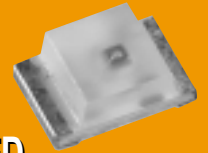
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Product Guide

D_1112H Series, Thin Type InGaN/SiC SMT LED



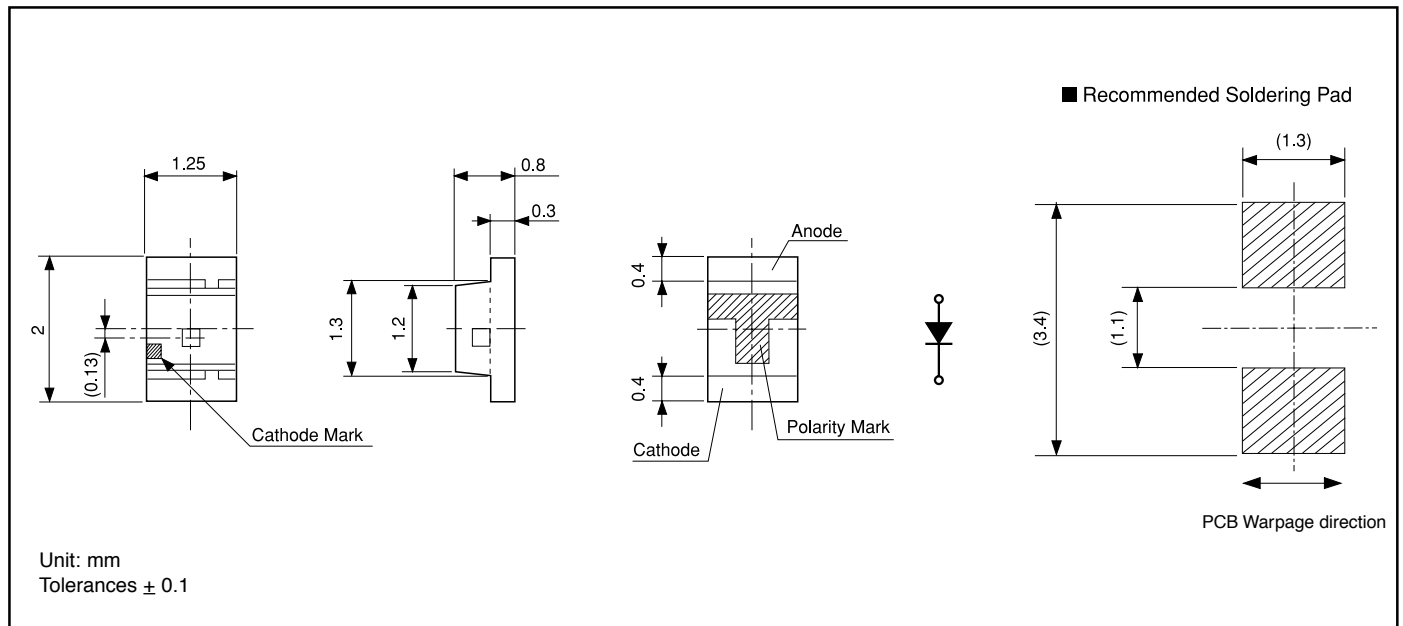
Features

- High brightness (InGaN/SiC) die material
- Available in green (525nm), bluish-green (505nm) and blue (470nm) colors
- Wide 150 degree viewing angle
- Reflow and dip soldering compatible
- 1000V minimum ESD protection

Applications

- Portable phone key pad backlight
- Various other backlight uses

Outline Dimensions



Electro-Optical Characteristics

($T_a=25^\circ\text{C}$)

Part No.	Material	Emitted Color	Lens Color	Luminous Intensity I_v			Wavelength				Forward Voltage V_F			Reverse Current I_R		Viewing Angle (2θ 1/2)	
				MIN.	TYP.	I_F	Peak λ_p TYP.	Dominant λ_d TYP.	Spectral Line Half Width $\Delta\lambda$ TYP.	I_F	TYP.	MAX.	I_F	MAX.	V_R		
DG1112H	InGaN/SiC	Green	Milky White	24	40	10	522	525	30	10	3.3	3.8	10	100	5	150°	
DC1112H	InGaN/SiC	Bluish-Green		24	34	10	502	505	30	10	3.3	3.8	10	100	5		
DB1112H	InGaN/SiC	Blue		8.5	14	10	467	470	26	10	3.3	3.8	10	100	5		
Units				mcd	mA		nm		mA		V		mA		μA	V	Deg.

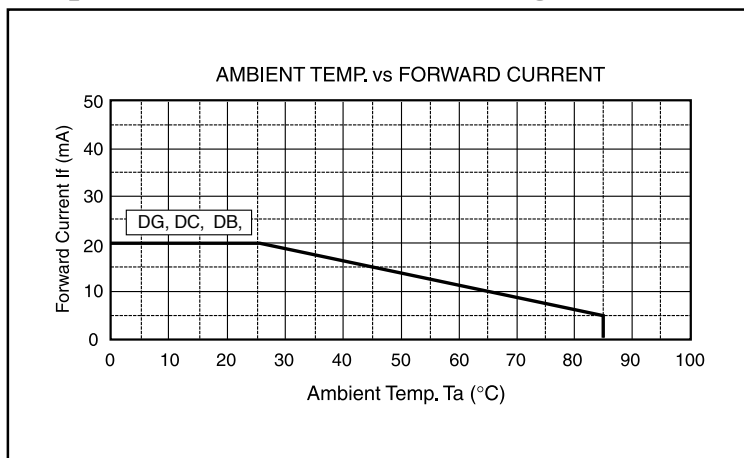
Absolute Maximum Ratings

(Ta=25°C)

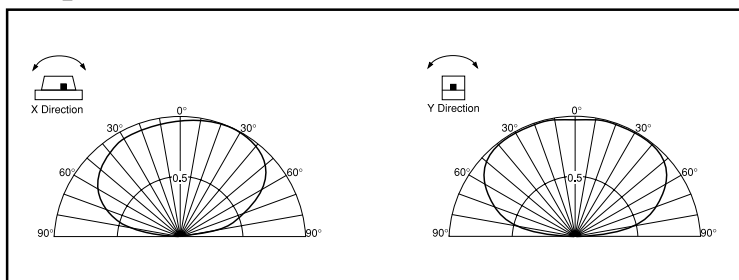
Item	Symbol	Green	Bluish-Green	Blue	Units
		DG	DC	DB	
Power Dissipation	Pd	76	76	76	mW
Forward Current	I _F	20	20	20	mA
Peak Forward Current	I _{FM}	48	48	48	mA
Reverse Voltage	V _R	5	5	5	V
Operating Temperature	Topr	-40 to +85			°C
Storage Temperature	Tstg	-40 to +100			°C
Derating*	ΔI _F	0.28 (DC) 0.69 (Pulse)			mA/°C

* Ta=25°C, I_{FM} applies for the pulse width ≤ 1msec. and duty cycle ≤ 1/20.

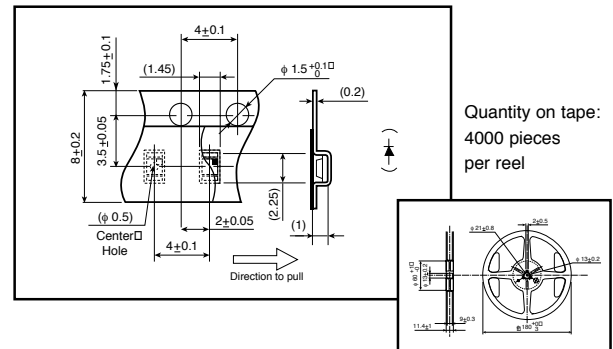
Operation Current Derating Chart (DC)



Spatial Distribution



Taping Specifications

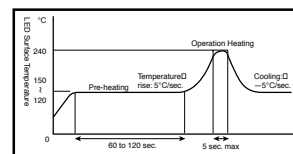


Precautions

Please follow these handling precautions to prevent damage to the chip and ensure its reliability.

1. Soldering conditions:

- **Soldering iron:** Temperature at tip of iron: 280°C max. (30W max.) Soldering time: 3 sec. max.
- **Dip soldering:** Preheating: 120 ~ 150°C max. (resin surface temp.) 60 ~ 120 sec. max. Bath temperature: 260°C max. Dipping Time: 5 sec. max.
- **Reflow Soldering:**



2. Cleaning:

- If cleaning is required, use the following solutions for less than 1 minute, at less than 40°C.
- Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Product specifications subject to change without notice. PGD1112H-0301